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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	33
Program Memory Size	7KB (4K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	192 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 6V
Data Converters	
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.59x16.59)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc65at-04i-l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clock and instruction execution flow is shown in Figure 3-5.

3.2 Instruction Flow/Pipelining

An "Instruction Cycle" consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g. GOTO) then two cycles are required to complete the instruction (Example 3-1).

A fetch cycle begins with the program counter (PC) incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the "Instruction Register (IR)" in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).



FIGURE 3-5: CLOCK/INSTRUCTION CYCLE

EXAMPLE 3-1: INSTRUCTION PIPELINE FLOW



All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is "flushed" from the pipeline while the new instruction is being fetched and then executed.

4.2.2.8 PCON REGISTER

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The Power Control register (PCON) contains a flag bit to allow differentiation between a Power-on Reset to an external MCLR reset or WDT reset. Those devices with brown-out detection circuitry contain an additional bit to differentiate a Brown-out Reset condition from a Poweron Reset condition.

Note: BOR is unknown on Power-on Reset. It must then be set by the user and checked on subsequent resets to see if BOR is clear, indicating a brown-out has occurred. The BOR status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (by clearing the BODEN bit in the Configuration word).

FIGURE 4-22: PCON REGISTER FOR PIC16C62/64/65 (ADDRESS 8Eh)



FIGURE 4-23: PCON REGISTER FOR PIC16C62A/R62/63/R63/64A/R64/65A/R65/66/67 (ADDRESS 8Eh)



Example 4-1 shows the calling of a subroutine in page 1 of the program memory. This example assumes that the PCLATH is saved and restored by the interrupt service routine (if interrupts are used).

EXAMPLE 4-1: CALL OF A SUBROUTINE IN PAGE 1 FROM PAGE 0

ORG 0x5	00	
BSF	PCLATH, 3	;Select page 1 (800h-FFFh)
BCF	PCLATH,4	;Only on >4K devices
CALL	SUB1_P1	;Call subroutine in
	:	;page 1 (800h-FFFh)
	:	
	:	
ORG 0x9	00	
SUB1_P1	:	;called subroutine
	:	;page 1 (800h-FFFh)
	:	
RETURN		;return to Call subroutine ;in page 0 (000h-7FFh)

4.5 Indirect Addressing, INDF and FSR Registers

Applicable	e Devices

61	62	62A	R62	63	R63	64	64A	R64	65	65A	R65	66	67
----	----	-----	-----	----	-----	----	-----	-----	----	-----	-----	----	----

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses the register pointed to by the File Select Register, FSR. Reading the INDF register itself indirectly (FSR = '0') will produce 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-25.

A simple program to clear RAM location 20h-2Fh using indirect addressing is shown in Example 4-2.

EXAMPLE 4-2: INDIRECT ADDRESSING

NEXT	movlw movwf clrf incf btfss	0x20 FSR INDF FSR,F FSR,4	;initialize pointer ; to RAM ;clear INDF register ;inc pointer ;all done?
	goto	NEXT	;NO, clear next
CONTINUE			
	:		;YES, continue

FIGURE 4-25: DIRECT/INDIRECT ADDRESSING



5.3 PORTC and TRISC Register

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

PORTC is an 8-bit wide bi-directional port. Each pin is individually configurable as an input or output through the TRISC register. PORTC is multiplexed with several peripheral functions (Table 5-5). PORTC pins have Schmitt Trigger input buffers.

When enabling peripheral functions, care should be taken in defining TRIS bits for each PORTC pin. Some peripherals override the TRIS bit to make a pin an output, while other peripherals override the TRIS bit to make a pin an input. Since the TRIS bit override is in effect while the peripheral is enabled, read-modifywrite instructions (BSF, BCF, XORWF) with TRISC as destination should be avoided. The user should refer to the corresponding peripheral section for the correct TRIS bit settings.

EXAMPLE 5-3: INITIALIZING PORTC



FIGURE 5-6: PORTC BLOCK DIAGRAM



3: Peripheral OE (output enable) is only activated if peripheral select is active.

TABLE 5-5: PORTC FUNCTIONS FOR PIC16C62/64

Name	Bit#	Buffer Type	Function
RC0/T1OSI/T1CKI	bit0	ST	Input/output port pin or Timer1 oscillator input or Timer1 clock input
RC1/T1OSO	bit1	ST	Input/output port pin or Timer1 oscillator output
RC2/CCP1	bit2	ST	Input/output port pin or Capture1 input/Compare1 output/PWM1 output
RC3/SCK/SCL	bit3	ST	RC3 can also be the synchronous serial clock for both SPI and I^2C modes.
RC4/SDI/SDA	bit4	ST	RC4 can also be the SPI Data In (SPI mode) or data I/O (I ² C mode).
RC5/SDO	bit5	ST	Input/output port pin or synchronous serial port data output
RC6	bit6	ST	Input/output port pin
RC7	bit7	ST	Input/output port pin

Legend: ST = Schmitt Trigger input

SWITCHING PRESCALER ASSIGNMENT 7.3.1

The prescaler assignment is fully under software control, i.e., it can be changed "on the fly" during program execution.

Note:	To avoid an unintended device RESET, the
	following instruction sequence (shown in
	Example 7-1) must be executed when
	changing the prescaler assignment from
	Timer0 to the WDT. This precaution must
	be followed even if the WDT is disabled.

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

	1)	BSF	STATUS, RPO	;Bank 1
Lines 2 and 3 do NOT have to	2)	MOVLW	b'xx0x0xxx'	;Select clock source and prescale value of
be included if the final desired	3)	MOVWF	OPTION_REG	;other than 1:1
prescale value is other than 1:1.	4)	BCF	STATUS, RPO	;Bank 0
a temporary prescale value is	5)	CLRF	TMR0	;Clear TMR0 and prescaler
set in lines 2 and 3 and the final	6)	BSF	STATUS, RP1	;Bank 1
prescale value will be set in lines	7)	MOVLW	b'xxxx1xxx'	;Select WDT, do not change prescale value
10 and 11.	8)	MOVWF	OPTION_REG	;
	9)	CLRWDT		;Clears WDT and prescaler
	10)	MOVLW	b'xxxx1xxx'	;Select new prescale value and WDT
	11)	MOVWF	OPTION_REG	;
	12)	BCF	STATUS, RPO	;Bank 0

To change prescaler from the WDT to the Timer0 module, use the sequence shown in Example 7-2.

EXAMPLE 7-2: CHANGING PRESCALER (WDT → TIMER0)

CLRWDT ;Clear WDT and prescaler BSF STATUS, RP0 ;Bank 1 MOVLW b'xxxx0xxx' ;Select TMR0, new prescale value and clock source MOVWF OPTION REG ; BCF STATUS, RPO ;Bank 0

TABLE 7-1: **REGISTERS ASSOCIATED WITH TIMER0**

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR, BOR	Value on all other resets
01h, 101h	TMR0	Timer0	module's r	egister						xxxx xxxx	uuuu uuuu
0Bh,8Bh, 10Bh,18Bh	INTCON	GIE	PEIE ⁽¹⁾	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
81h, 181h	OPTION	RBPU	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	_	PORTA Data	Direction F	Register ⁽¹⁾				11 1111	11 1111

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by Timer0.

10.3 PWM Mode

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

In Pulse Width Modulation (PWM) mode, the CCP1 pin produces up to a 10-bit resolution PWM output. Since the CCP1 pin is multiplexed with the PORTC data latch, the TRISC<2> bit must be cleared to make the CCP1 pin an output.

Note: Clearing the CCP1CON register will force the CCP1 PWM output latch to the default low level. This is not the PORTC I/O data latch.

Figure 10-4 shows a simplified block diagram of the CCP module in PWM mode.

For a step by step procedure on how to set up the CCP module for PWM operation, see Section 10.3.3.

FIGURE 10-4: SIMPLIFIED PWM BLOCK DIAGRAM



A PWM output (Figure 10-5) has a time base (period) and a time that the output stays high (duty cycle). The frequency of the PWM is the inverse of the period (1/period).

FIGURE 10-5: PWM OUTPUT



10.3.1 PWM PERIOD

The PWM period is specified by writing to the PR2 register. The PWM period can be calculated using the following formula:

PWM period = [(PR2) + 1] • 4 • TOSC • (TMR2 prescale value)

PWM frequency is defined as 1 / [PWM period].

When TMR2 is equal to PR2, the following three events occur on the next increment cycle:

- TMR2 is cleared
- The PWM duty cycle is latched from CCPR1L into CCPR1H
- The CCP1 pin is set (exception: if PWM duty cycle = 0%, the CCP1 pin will not be set)

Note:	The Timer2 postscaler (see Section 9.1) is
	not used in the determination of the PWM
	frequency. The postscaler could be used to
	have a servo update rate at a different fre-
	quency than the PWM output.

10.3.2 PWM DUTY CYCLE

The PWM duty cycle is specified by writing to the CCPR1L register and to the CCP1CON<5:4> bits. Up to 10-bit resolution is available: the CCPR1L contains the eight MSbs and the CCP1CON<5:4> contains the two LSbs. This 10-bit value is represented by CCPR1L:CCP1CON<5:4>. The following equation is used to calculate the PWM duty cycle in time:

PWM duty cycle = (CCPR1L:CCP1CON<5:4>) • Tosc • (TMR2 prescale value)

CCPR1L and CCP1CON<5:4> can be written to at any time, but the duty cycle value is not latched into CCPR1H until after a match between PR2 and TMR2 occurs (i.e., the period is complete). In PWM mode, CCPR1H is a read-only register.

The CCPR1H register and a 2-bit internal latch are used to double buffer the PWM duty cycle. This double buffering is essential for glitchless PWM operation.

When the CCPR1H and 2-bit latch match TMR2 concatenated with an internal 2-bit Q clock or 2 bits of the TMR2 prescaler, the CCP1 pin is cleared.

Maximum PWM resolution (bits) for a given PWM frequency:

$$= \frac{\log\left(\frac{FOSC}{FPWM}\right)}{\log(2)} \quad \text{bits}$$

Note: If the PWM duty cycle value is longer than the PWM period the CCP1 pin will not be forced to the low level.

To enable the serial port, SSP Enable bit, SSPEN (SSPCON<5>) must be set. To reset or reconfigure SPI mode, clear bit SSPEN, re-initialize the SSPCON register, and then set bit SSPEN. This configures the SDI, SDO, SCK, and SS pins as serial port pins. For the pins to behave as the serial port function, they must have their data direction bits (in the TRISC register) appropriately programmed. That is:

- SDI must have TRISC<4> set
- SDO must have TRISC<5> cleared
- SCK (Master mode) must have TRISC<3> cleared
- SCK (Slave mode) must have TRISC<3> set
- SS must have TRISA<5> set

Any serial port function that is not desired may be overridden by programming the corresponding data direction (TRIS) register to the opposite value. An example would be in master mode where you are only sending data (to a display driver), then both SDI and \overline{SS} could be used as general purpose outputs by clearing their corresponding TRIS register bits.

Figure 11-10 shows a typical connection between two microcontrollers. The master controller (Processor 1) initiates the data transfer by sending the SCK signal. Data is shifted out of both shift registers on their programmed clock edge, and latched on the opposite edge of the clock. Both processors should be programmed to same Clock Polarity (CKP), then both controllers would send and receive data at the same time. Whether the data is meaningful (or dummy data) depends on the application firmware. This leads to three scenarios for data transmission:

- · Master sends data Slave sends dummy data
- Master sends data Slave sends data
- · Master sends dummy data Slave sends data

The master can initiate the data transfer at any time because it controls the SCK. The master determines when the slave (Processor 2) is to broadcast data by the firmware protocol.

In master mode the data is transmitted/received as soon as the SSPBUF register is written to. If the SPI is only going to receive, the SCK output could be disabled (programmed as an input). The SSPSR register will continue to shift in the signal present on the SDI pin at the programmed clock rate. As each byte is received, it will be loaded into the SSPBUF register as if a normal received byte (interrupts and status bits appropriately set). This could be useful in receiver applications as a "line activity monitor" mode.

In slave mode, the data is transmitted and received as the external clock pulses appear on SCK. When the last bit is latched the interrupt flag bit SSPIF (PIR1<3>) is set.

The clock polarity is selected by appropriately programming bit CKP (SSPCON<4>). This then would give waveforms for SPI communication as shown in Figure 11-11, Figure 11-12, and Figure 11-13 where the MSB is transmitted first. In master mode, the SPI clock rate (bit rate) is user programmable to be one of the following:

- Fosc/4 (or Tcy)
- Fosc/16 (or 4 Tcy)
- Fosc/64 (or 16 Tcy)
- Timer2 output/2

This allows a maximum bit clock frequency (at 20 MHz) of 5 MHz. When in slave mode the external clock must meet the minimum high and low times.

In sleep mode, the slave can transmit and receive data and wake the device from sleep.



FIGURE 11-10: SPI MASTER/SLAVE CONNECTION (PIC16C66/67)

11.5.1.2 RECEPTION

When the R/\overline{W} bit of the address byte is clear and an address match occurs, the R/\overline{W} bit of the SSPSTAT register is cleared. The received address is loaded into the SSPBUF register.

When the address byte overflow condition exists, then no acknowledge (\overline{ACK}) pulse is given. An overflow condition is defined as either bit BF (SSPSTAT<0>) is set or bit SSPOV (SSPCON<6>) is set. An SSP interrupt is generated for each data transfer byte. Flag bit SSPIF (PIR1<3>) must be cleared in software. The SSPSTAT register is used to determine the status of the byte.

FIGURE 11-25: I²C WAVEFORMS FOR RECEPTION (7-BIT ADDRESS)

Receiving Address R/W=0 Receiving Data ACK Receiving Data ACK SDA /A7_ A6 A5 A4 A3 A2 A1 ACK D7 D6 D5 D4 D3 D2 D1 D0 D7 D6 D5 D4 D3 D2 D1 D0 D3 D2 D1 D0 S0 A7 A6 A5 A4 A3 A2 A1 D5 D6 D5 D4 D3 D2 D1 D0 D3 D2 D1 D0 C ACK ACK ACK ACK ACK D3 D2 D1 D0 D3 D2 D1 D0 C ACK ACK	
SSPIF (PIR1<3>) Cleared in software BF (SSPSTAT<0>) SSPBUF register is read	Bus Master terminates transfer
SSPOV (SSPCON<6>) Bit SSPOV is set because the SSPBUF register is still full.	
ACK is not sent.	

13.0 SPECIAL FEATURES OF THE CPU

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

What sets a microcontroller apart from other processors are special circuits to deal with the needs of realtime applications. The PIC16CXX family has a host of such features intended to maximize system reliability, minimize cost through elimination of external components, provide power saving operating modes and offer code protection. These are:

- Oscillator selection
- Reset
 - Power-on Reset (POR)
 - Power-up Timer (PWRT)
 - Oscillator Start-up Timer (OST)
 - Brown-out Reset (BOR)
- Interrupts
- Watchdog Timer (WDT)
- SLEEP mode
- · Code protection
- ID locations
- · In-circuit serial programming

The PIC16CXX has a Watchdog Timer which can be shut off only through configuration bits. It runs off its own RC oscillator for added reliability. There are two timers that offer necessary delays on power-up. One is the Oscillator Start-up Timer (OST), intended to keep the chip in RESET until the crystal oscillator is stable. The other is the Power-up Timer (PWRT), which provides a fixed delay of 72 ms (nominal) on power-up only, designed to keep the part in reset while the power supply stabilizes. With these two timers on-chip, most applications need no external reset circuitry.

SLEEP mode is designed to offer a very low current power-down mode. The user can wake from SLEEP through external reset, Watchdog Timer Wake-up or through an interrupt. Several oscillator options are also made available to allow the part to fit the application. The RC oscillator option saves system cost while the LP crystal option saves power. A set of configuration bits are used to select various options.

13.1 Configuration Bits

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The configuration bits can be programmed (read as '0') or left unprogrammed (read as '1') to select various device configurations. These bits are mapped in program memory location 2007h.

The user will note that address 2007h is beyond the user program memory space. In fact, it belongs to the special test/configuration memory space (2000h - 3FFFh), which can be accessed only during programming.

FIGURE 13-1: CONFIGURATION WORD FOR PIC16C61

— ·		_	_	-	_	_	-	CP0	PWRTE	WDTE	FOSC1	FOSC0 bit0	Register: Address	CONFIG 2007h
bit 13-5:	Unimplen	nented	Read	as '1'									L	
bit 4:	CP0 : Code 1 = Code 0 = All me	e protec protecti mory is	ction bit on off code p	t protecte	d, but (00h - 3F	h is wr	itable						
bit 3:	PWRTE : F 1 = Power 0 = Power	Power-u -up Tim -up Tim	ip Time ier enal ier disa	r Enable bled bled	e bit									
bit 2:	WDTE : Wa 1 = WDT e 0 = WDT e	atchdog enabled disabled	g Timer I d	Enable	bit									
bit 1-0:	FOSC1:F0 11 = RC o 10 = HS o 01 = XT o 00 = LP o	DSC0: oscillato oscillato scillato scillato	Oscillat r r r	or Sele	ction bi	ts								

13.3 <u>Reset</u>

Applicable Devices

61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

The PIC16CXX differentiates between various kinds of reset:

- · Power-on Reset (POR)
- MCLR reset during normal operation
- MCLR reset during SLEEP
- WDT Reset (normal operation)
- Brown-out Reset (BOR) Not on PIC16C61/62/ 64/65

Some registers are not affected in any reset condition, their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-on Reset (POR), on MCLR or WDT Reset, on MCLR reset during SLEEP, and on Brownout Reset (BOR). They are not affected by a WDT Wake-up, which is viewed as the resumption of normal operation.

The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits are set or cleared differently in different reset situations as indicated in Table 13-7, Table 13-8, and Table 13-9. These bits are used in software to determine the nature of the reset. See Table 13-12 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 13-9.

On the PIC16C62A/R62/63/R63/64A/R64/65A/R65/ 66/67, the MCLR reset path has a noise filter to detect and ignore small pulses. See parameter #34 for pulse width specifications.

It should be noted that a WDT Reset does not drive the $\overline{\text{MCLR}}$ pin low.



FIGURE 13-9: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

17.4 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2pp	S	3. TCC:ST	(I ² C specifications only)				
2. TppS		4. Ts	(I ² C specifications only)				
Т							
F	Frequency	Т	Time				
Lowercas	se letters (pp) and their meanings:						
рр							
сс	CCP1	OSC	OSC1				
ck	CLKOUT	rd	RD				
CS	CS	rw	RD or WR				
di	SDI	SC	SCK				
do	SDO	SS	SS				
dt	Data in	tO	TOCKI				
io	I/O port	t1	T1CKI				
mc	MCLR	wr	WR				
Uppercas	se letters and their meanings:						
S							
F	Fall	P	Period				
Н	High	R	Rise				
I	Invalid (Hi-impedance)	V	Valid				
L	Low	Z	Hi-impedance				
I ² C only							
AA	output access	High	High				
BUF	Bus free	Low	Low				
TCC:ST (l	² C specifications only)						
CC							
HD	Hold	SU	Setup				
ST							
DAT	DATA input hold	STO	STOP condition				
STA	START condition						
FIGURE 17	7-1: LOAD CONDITIONS FOR DEVICE	TIMING SP	ECIFICATIONS				
	Load condition 1 VDD/2		Load condition 2				
	Ŷ						
			\checkmark				
	\leq "						
		F					
			▼ Via				
	Pin		VSS				
	▼ Vee						
RL = 464	4Ω	No	ote 1: PORTD and PORTE are not imple-				
$C_{I} = 50$	CL = 50 pE for all pips except OSC2/CLKOLIT mented on the PIC16C62.						
02 - 50	but including D and E outputs as ports						
15	pF for OSC2 output						

19.3

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

DC Characteristics: PIC16C65-04 (Commercial, Industrial) PIC16C65-10 (Commercial, Industrial) PIC16C65-20 (Commercial, Industrial) PIC16LC65-04 (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise stated)							
		Operati	ng tempera	ature	-40°C	; ≤ T.	$A \le +85^{\circ}C$ for industrial and		
DC CHA	RACTERISTICS				0°C	≤ T.	$A \le +70^{\circ}C$ for commercial		
		Operating voltage VDD range as described in DC spec Section 19.1 an							
_	••••••	Section	19.2	-			• ••••		
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions		
INO.				Т					
	Input Low Voltage								
	I/O ports	VIL							
D030	with TTL buffer		Vss	-	0.15VDD	V	For entire VDD range		
D030A			Vss	-	0.8V	V	$4.5V \leq VDD \leq 5.5V$		
D031	with Schmitt Trigger buffer		Vss	-	0.2VDD	V			
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2VDD	V			
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1		
	Input High Voltage								
	I/O ports	Vін		-					
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \leq V_{DD} \leq 5.5V$		
D040A			0.25VDD+	-	Vdd	V	For entire VDD range		
			0.8V						
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd		For entire VDD range		
D042	MCLR		0.8VDD	-	Vdd	V			
D042A	OSC1 (XT, HS and LP)		0.7 Vdd	-	Vdd	V	Note1		
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V			
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS		
	Input Leakage Current								
	(Notes 2, 3)								
D060	I/O ports	lı∟	-	-	±1	μA	$Vss \le VPIN \le VDD$, Pin at hi-		
							impedance		
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \leq V PIN \leq V DD$		
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS, and		
							LP osc configuration		
	Output Low Voltage								
D080	I/O ports	VOL	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5 V,		
							-40°C to +85°C		
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5 V,		
							-40°C to +85°C		
	Output High Voltage								
D090	I/O ports (Note 3)	VOH	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V,		
							-40°C to +85°C		
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V,		
							-40°C to +85°C		
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin		

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 19-3: CLKOUT AND I/O TIMING



TABLE 19-3-	CLKOUT AND I/O TIMING REQUIREMENTS.
TADLL 13-3.	

Parameter	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
No.								
10*	TosH2ckL	OSC1↑ to CLKOUT↓		_	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑		_	75	200	ns	Note 1
12*	TckR	CLKOUT rise time		—	35	100	ns	Note 1
13*	TckF	CLKOUT fall time		—	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT \downarrow to Port out valid		—		0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑		0.25Tcy + 25		_	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑		0		_	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		—	50	150	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port	PIC16 C 65	100		_	ns	
		input invalid (I/O in hold time)	PIC16 LC 65	200		_	ns	
19*	TioV2osH	Port input valid to OSC1 [↑] (I/O i	n setup time)	0		_	ns	
20*	TioR	Port output rise time	PIC16 C 65	—	10	25	ns	
			PIC16 LC 65	—		60	ns	
21*	TioF	Port output fall time	PIC16 C 65	—	10	25	ns	
			PIC16 LC 65	—		60	ns	
22††*	Tinp	RB0/INT pin high or low time		Тсү	-	—	ns	
23††*	Trbp	RB7:RB4 change int high or low	w time	TCY	_	_	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

these parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

Applicable Devices	61	62	62A	B62	63	B63	64	64A	B64	65	65A	B65	66	67
Applicable Berliebe	•••	02	00,0	1102	00	1100	•••	0.0.1	1101	00	0071	1100	00	0.

Standard Operating Conditions (unless otherwise stated)									
		Operating temperature $-40^{\circ}C \leq TA \leq +125^{\circ}C$ for extended,							
			•		-40°C	C ≤ T	$A \le +85^{\circ}C$ for industrial and		
DC CHA	RACTERISTICS				0°C	≤T	$A \le +70^{\circ}C$ for commercial		
		Operating voltage VDD range as described in DC spec Section 20.1 and							
		Section	20.2		-				
Param	Characteristic	Sym	Min	Тур	Max	Units	Conditions		
No.		-		†					
	Output High Voltage								
D090	I/O ports (Note 3)	Vон	VDD-0.7	-	-	V	IOH = -3.0 mA, VDD = 4.5V, -40°С to +85°С		
D090A			Vdd-0.7	-	-	V	IOH = -2.5 mA, VDD = 4.5V, -40°C to +125°C		
D092	OSC2/CLKOUT (RC osc config)		VDD-0.7	-	-	V	IOH = -1.3 mA, VDD = 4.5V, -40°С to +85°С		
D092A			VDD-0.7	-	-	V	IOH = -1.0 mA, VDD = 4.5V, -40°С to +125°С		
D150*	Open-Drain High Voltage	Vod	-	-	14	V	RA4 pin		
	Capacitive Loading Specs on Out- put Pins								
D100	OSC2 pin	Cosc2	-	-	15	pF	In XT, HS and LP modes when external clock is used to drive OSC1.		
D101	All I/O pins and OSC2 (in RC mode)	CIO	-	-	50	pF			
D102	SCL, SDA in I ² C mode	Cb	-	-	400	pF			

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

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FIGURE 20-12: USART SYNCHRONOUS TRANSMISSION (MASTER/SLAVE) TIMING



TABLE 20-11: USART SYNCHRONOUS TRANSMISSION REQUIREMENTS

Parameter No.	Sym	Characteristic	aracteristic			Max	Units	Conditions
120*	TckH2dtV	SYNC XMIT (MASTER & SLAVE)	PIC16 C 63/65A		—	80	ns	
		Clock high to data out valid	PIC16 LC 63/65A	-	—	100	ns	
121*	Tckrf Clock out rise time and fall time		PIC16 C 63/65A		_	45	ns	
		(Master Mode)	PIC16 LC 63/65A	-	—	50	ns	
122*	Tdtrf	Data out rise time and fall time	PIC16 C 63/65A		_	45	ns	
			PIC16 LC 63/65A	-	—	50	ns	
* Thee	a naramatara	are characterized but not tested						

These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 20-13: USART SYNCHRONOUS RECEIVE (MASTER/SLAVE) TIMING



TABLE 20-12: USART SYNCHRONOUS RECEIVE REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
125*	TdtV2ckL	$\frac{\text{SYNC RCV (MASTER \& SLAVE)}}{\text{Data setup before CK} \downarrow (\text{DT setup time})}$	15	_	_	ns	
126*	TckL2dtl	Data hold after CK \downarrow (DT hold time)	15	—	_	ns	

These parameters are characterized but not tested.

†: Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

FIGURE 21-3: CLKOUT AND I/O TIMING



TABLE 21-3: CLKOUT AND I/O TIMING REQUIREMENT

Param	Sym	Characteristic	<	Min	Typt	Max	Units	Conditions
No.				$\langle - \rangle \langle$	\sum			
10*	TosH2ckL	OSC1↑ to CLKOUT↓		$\langle \mathcal{F} \rangle$	75	200	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑			75	200	ns	Note 1
12*	TckR	CLKOUT rise time	$\sim V $	\searrow	35	100	ns	Note 1
13*	TckF	CLKOUT fall time	\sum	> -	35	100	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid	$ _{A} _{\wedge}$	[_		0.5TCY + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT	$///\sim$	Tosc + 200	-	_	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑	$\overline{\langle \langle \rangle}$	0	I	_	ns	Note 1
17*	TosH2ioV	OSC1 [↑] (Q1 cycle) to Port out val	id 🔪	—	50	150	ns	
18*	TosH2ioI	OSC11 (Q2 cycle) to Port input	P1C16CR63/R65	100		_	ns	
		invalid (I/O in hold time)	PIC16LCR63/R65	200		_	ns	
19*	TioV2osH	Port input valid to OSC11 (I/Q in	setup time)	0	_	—	ns	
20*	TioR	Port output rise time	PIC16CR63/R65	—	10	40	ns	
		\frown	PIC16LCR63/R65	_	-	80	ns	
21*	TioF	Port output fall time	PIC16CR63/R65	_	10	40	ns	
	\langle	$\langle \rangle \rangle$	PIC16LCR63/R65	—		80	ns	
22††*	Tinp	INT pin high or low time		Тсү	-	_	ns	
23††*	Trbp	RB7:RB2 change INT high or low	time	Тсү	_	—	ns	

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

t† These parameters are asynchronous events not related to any internal clock edge.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67

22.3 DC Characteristics: PIC16C66/67-04 (Commercial, Industrial, Extended) PIC16C66/67-10 (Commercial, Industrial, Extended) PIC16C66/67-20 (Commercial, Industrial, Extended) PIC16LC66/67-04 (Commercial, Industrial)

		Standard Operating Conditions (unless otherwise stated) Operating temperature $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended,							
DC CHA	ARACTERISTICS				-40°0	C ≤1	$A \leq +85^{\circ}C$ for industrial and		
		Operation and Second	ng voltage ction 22.2	e Vde	0°C range as	lescrit	$a \le +70^{\circ}C$ for commercial bed in DC spec Section 22.1		
Param No.	Characteristic	Sym	Min	Typ t	Max	Units	Conditions		
	Input Low Voltage			-					
	I/O ports	VIL							
D030 D030A	with TTL buffer		Vss Vss	-	0.15VDD 0.8V	v v	For entire VDD range $4.5V \le VDD \le 5.5V$		
D031	with Schmitt Trigger buffer		Vss	-	0.2Vdd	V			
D032	MCLR, OSC1 (in RC mode)		Vss	-	0.2Vdd	V			
D033	OSC1 (in XT, HS and LP)		Vss	-	0.3VDD	V	Note1		
	Input High Voltage								
	I/O ports	Vін		-					
D040	with TTL buffer		2.0	-	Vdd	V	$4.5V \le VDD \le 5.5V$		
D040A			0.25VDD + 0.8V	-	Vdd	V	For entire VDD range		
D041	with Schmitt Trigger buffer		0.8VDD	-	Vdd	v	For entire VDD range		
D042	MCLR		0.8VDD	-	Vdd	v	_		
D042A	OSC1 (XT, HS and LP)		0.7Vdd	-	Vdd	V	Note1		
D043	OSC1 (in RC mode)		0.9Vdd	-	Vdd	V			
D070	PORTB weak pull-up current	IPURB	50	250	400	μA	VDD = 5V, VPIN = VSS		
	Input Leakage Current (Notes 2, 3)								
D060	I/O ports	lı∟	-	-	±1	μA	Vss \leq VPIN \leq VDD, Pin at hi-impedance		
D061	MCLR, RA4/T0CKI		-	-	±5	μA	$Vss \le VPIN \le VDD$		
D063	OSC1		-	-	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP osc configuration		
	Output Low Voltage								
D080	I/O ports	Vol	-	-	0.6	V	IOL = 8.5 mA, VDD = 4.5V, -40°C to +85°C		
D080A			-	-	0.6	V	IOL = 7.0 mA, VDD = 4.5V, -40°C to +125°C		
D083	OSC2/CLKOUT (RC osc config)		-	-	0.6	V	IOL = 1.6 mA, VDD = 4.5V, -40°C to +85°C		
D083A			-	-	0.6	V	IOL = 1.2 mA, VDD = 4.5V, -40°C to +125°C		

These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: In RC oscillator configuration, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC16C6X be driven with external clock in RC mode.

 The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.

*

Applicable Devices 61 62 62A R62 63 R63 64 64A R64 65 65A R65 66 67



FIGURE 23-23: TYPICAL XTAL STARTUP TIME vs. Vdd (HS MODE, 25°C)



FIGURE 23-24: TYPICAL XTAL STARTUP TIME vs. Vdd (XT MODE, 25°C)



TABLE 23-2: CAPACITOR SELECTION FOR CRYSTAL OSCILLATORS

Osc Type	Crystal Freq	Cap. Range C1	Cap. Range C2
LP	32 kHz	33 pF	33 pF
	200 kHz	15 pF	15 pF
ХТ	200 kHz	47-68 pF	47-68 pF
	1 MHz	15 pF	15 pF
	4 MHz	15 pF	15 pF
HS	4 MHz	15 pF	15 pF
	8 MHz	15-33 pF	15-33 pF
	20 MHz	15-33 pF	15-33 pF
Crystals Used			
32 kHz	Epson C-00	01R32.768K-A	± 20 PPM
200 kHz	STD XTL 2	00.000KHz	± 20 PPM
1 MHz	ECS ECS-1	± 50 PPM	
4 MHz	ECS ECS-4	± 50 PPM	
8 MHz	EPSON CA	± 30 PPM	
20 MHz	EPSON CA	-301 20.000M-C	± 30 PPM

24.11 44-Lead Plastic Leaded Chip Carrier (Square) (PLCC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Package Group: Plastic Leaded Chip Carrier (PLCC)						
	Millimeters			Inches		
Symbol	Min	Мах	Notes	Min	Max	Notes
А	4.191	4.572		0.165	0.180	
A1	2.413	2.921		0.095	0.115	
D	17.399	17.653		0.685	0.695	
D1	16.510	16.663		0.650	0.656	
D2	15.494	16.002		0.610	0.630	
D3	12.700	12.700	Reference	0.500	0.500	Reference
E	17.399	17.653		0.685	0.695	
E1	16.510	16.663		0.650	0.656	
E2	15.494	16.002		0.610	0.630	
E3	12.700	12.700	Reference	0.500	0.500	Reference
Ν	44	44		44	44	
CP	_	0.102		_	0.004	
LT	0.203	0.381		0.008	0.015	

-